

Product Family	Thin SOI		HM UNIBOND™	Thick SOI			Epiwafers		Application-specific substrates					Transfer services	
Products by Applications	Ultra-Thin UNIBOND™ XUT, XUT+	Ultra-Thin UNIBOND™ UTSOI	sSOI	UNIBOND™	UNIBOND™ + Epi	Engineered BSOI	EpiGaAs	Thin EpiGaN	SopSiC™	Anti-sticking BSOI	D-BSOI™	Multi SOI	Si-Si	Layer transfer services	Circuit transfer services
CMOS logic	●	●	●												●
Power management ICs				●	●	●			●					●	
Analog & mixed signal	●			●	●	●				●				●	
RF & microwave components	●			●	●		●	●	●					●	●
Discrete power devices					●	●		●	●		●		●	●	
Radiation hard & high temperature ICs	●			●	●	●									
Imaging					●	●									●
M(O)EMS	●			●	●	●				●	●	●		●	
Memories	●														●
Silicon photonics	●											●			
Solid state lighting															●

● Current offering



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